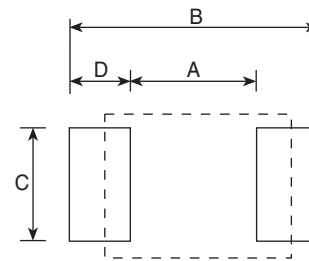




### standard soldering pad dimensions

The optimum soldering pad dimensions may differ depending on soldering conditions, however, the following land dimensions are generally recommended.

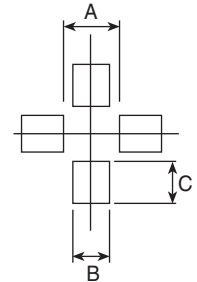
Type	Style	Dimensions millimeters				
		Component Size	A	B	C	D
WK73	2H	2.5 X 5.0	1.0	3.5	5.0	1.25
	2J	3.1 X 4.6	1.6	3.9	4.75	1.15
	3A	3.1 X 6.4	1.6	3.9	6.4	1.15
RK73 SG73 RN73 RN73H SR73 LT73 NT73 PT72 LA73 RF73 KL73 HV73 LP73 SDT73	1F	0.4 X 0.2	0.12	0.48	0.18	0.18
	1H	0.6 X 0.3	0.25	0.7	0.3	0.225
	1E	1.0 X 0.5	0.5	1.3	0.3	0.4
	1J	1.6 X 0.8	1.0	2.0	0.6	0.5
	2A	2.0 X 1.25	1.3	2.5	1.05	0.6
	2B	3.2 X 1.6	2.2	4.0	1.4	0.9
	2E	3.2 X 2.5	2.2	4.0	2.3	0.9
	2H	5.0 X 2.5	3.3	6.1	2.3	1.4
	3A	6.4 X 3.2	4.6	8.0	3.0	1.7
	07	5.0 X 2.5	2.3	7.0	2.6	2.35
SL/TSL	1	6.3 X 3.1	3.4	8.0	3.0	2.3
	2-3	11.5 X 7.0	5.4	15.0	5.0	4.8
SLN	2	11.5 X 7.0	5.0	15.0	6.0	5.0
NPR	1	7.5 X 4.5	4.0	10.0	3.0	3.0
	2	12.0 X 8.0	8.0	15.0	4.0	3.5
CCP	2E	3.2 X 2.5	2.2	5.0	2.0	1.4
	2B	3.2 X 1.6	2.2	5.0	1.4	1.4
CCF	1N	6.0 X 2.5	3.0	7.2	2.8	2.1
	1F	6.0 X 2.5	3.2	8.8	5.0	2.8
LPC	4045	4.5 X 4.0	1.5	5.1	3.5	1.8
	4235	4.5 X 4.2	1.9	5.5	2.6	1.8
	4545	4.1 X 4.6	2.9	5.3	4.7	1.2
	9040N	9.0 X 4.8	4.0	2.6	3.0	—
	9040E	9.0 X 4.8	4.0	2.6	3.0	—
	10065	10.0 X 10.4	5.0	13.0	6.0	4.0
KL	32	3.2 X 2.5	2.2	5.0	2.0	1.4
	KQT	0402	1.0 X 0.5	0.46	1.18	0.66
KQ KQC	0603	1.6 X 1.0	0.64	1.92	1.02	0.64
	0805	2.0 X 1.5	0.76	2.8	1.78	1.02
	1008	2.5 X 2.2	1.27	3.31	2.54	1.02
CZB CZP MHL MCL	1E	0.50 X 0.10	0.4	1.6	0.6	—
	1J	0.80 X 1.6	0.55	2.6	0.94	—
	2A	1.25 X 2.0	0.66	3.0	1.45	—
	2B	1.6 X 3.2	1.5	4.4	1.8	—
SDR	0603,0604	5.6 X 4.5	1.7	6.0	5.8	—
	0805	7.5 X 7.5	2.4	7.8	8.0	2.7
	1006	9.5 X 9.5	2.8	10.0	10.0	3.6

### Flat Type Components



 Soldering Pad  
 Chip Component

### LPC 9040N



Type	Style	Dimensions millimeters				
		Component Size	A	B	C	D
TF	10	1.0 X 0.5	0.5	1.3	0.3	0.4
	16	1.6 X 0.8	1.0	2.0	0.6	0.5
TLR	1E	1.0 X 0.5	0.2	1.3	0.6	0.55
	2A	2.0 X 1.25	0.5	2.5	1.3	1.0
	2BN, 2B	3.2 X 1.6	1.4	4.0	1.8	1.3
	2H(1mΩ)	5.0 X 2.5	1.0	6.1	3.0	2.55
	2H (2mΩ~6mΩ)	5.0 X 2.5	1.3	6.1	3.0	2.4
	2H (7mΩ~10mΩ)	5.0 X 2.5	3.3	6.1	3.0	1.4
	3A(1mΩ)	6.35 X 3.18	1.45	7.55	3.83	3.05
	3A(2mΩ)	6.35 X 3.18	3.45	7.55	3.83	2.05
	3A(3mΩ)	6.35 X 3.18	2.45	7.55	3.83	2.70
	3A(4mΩ)	6.35 X 3.18	3.45	7.55	3.83	2.05
TLRH	3AW (1mΩ~4mΩ)	6.35 X 3.18	1.45	7.55	3.83	3.05
	3AW (5mΩ~8mΩ)	6.35 X 3.18	3.45	7.55	3.83	2.05
	3AW (9mΩ~10mΩ)	6.35 X 3.18	4.40	7.55	3.83	1.575
	2H	5.0 X 2.5	3.3	6.1	3.0	1.4
UR73	3AW	6.3 X 3.2	4.4	7.5	3.7	1.55
	2A	2.0 X 1.25	1.3	3.1	1.25	0.9
UR73D	2B	3.2 X 1.6	2.2	4.4	1.6	1.1
	1E	1.0 X 0.5	0.5	1.8	0.5	0.65
	1J	1.6 X 0.8	0.5	2.5	0.9	1.0
	2A	2.0 X 1.25	0.8	3.4	1.3	1.3
UR73D	2B	3.2 X 1.6	1.2	4.6	1.8	1.7
	2H (10mΩ~30mΩ)	5.0 X 2.5	1.8	6.1	2.6	2.5
	2H (33mΩ~100mΩ)	5.0 X 2.5	3.3	6.1	2.5	1.4
	3A (10mΩ~30mΩ)	6.4 X 3.2	2.3	8.0	3.3	1.7
	3A (33mΩ~100mΩ)	6.4 X 3.2	4.6	8.0	3.0	1.7

Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use.

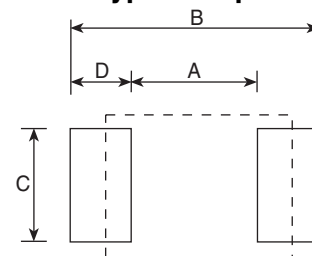
1/06/13



### standard soldering pad dimensions (continued)

The optimum soldering pad dimensions may differ depending on soldering conditions, however, the following land dimensions are generally recommended.

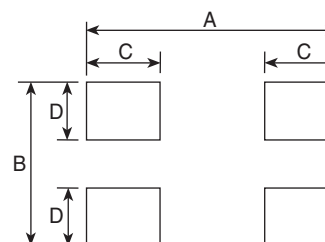
Type	Style	Dimensions millimeters					
		Component Size	A	B	C	D	
NV73 NV73DL	1H	0.6 X 0.3	0.25-0.35	0.65-0.95	0.25-0.35	0.2-0.3	
	1E	1.0 X 0.5	0.51	1.73	0.51	0.61	
	1J	1.6 X 0.8	1.0	3.0	1.2	1.0	
	2A	2.0 X 1.25	1.2	4.0	1.0	1.4	
	2B	3.2 X 1.6	2.2	5.0	1.3	1.4	
	2E	3.2 X 2.5	2.2	5.0	2.2	1.4	
	2J	4.5 X 3.2	3.0	5.8	2.9	1.4	
	2L	5.7 X 5.0	4.5	7.5	4.7	1.5	
NV73DS	2L	6.1 X 5.1	4.5	7.5	4.7	1.5	
SDS	0804 0805	8.0 X 10.5	5.7	10.5	2.2	2.4	
	1003 1005	10.0 X 12.7	7.3	13.3	2.8	3.0	
	0908	9.5 X 10.5	10.3	14.7	9.0	2.2	
	1205 1206 1208	12.7 X 12.7	6.0	14.0	7.0	4.0	
PS	B(0.75mΩ)	10.0 X 8.4	2.8	10.7	8.9	3.95	
	B(1mΩ)	10.0 X 8.4	3.8	10.7	8.9	3.95	
	B(0.2mΩ)	10.0 X 8.4	2.2	10.8	9.0	4.30	
	I	10.0 X 5.2	5.6	11.0	6.2	2.7	
	E	6.4 X 6.4	1.4	7.6	7.0	3.1	
SLF	0905	—	9.5	3.74	2.0	1.2	
LCM	1060	10 X 10	5.6	10.7	3.2	2.5	

### Flat Type Components



 Soldering Pad  
 Chip Component

### SLF



### surface mount inductor—SDR

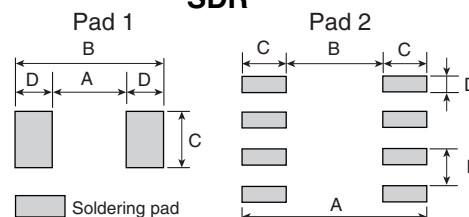
Dimensions millimeters						
Style	Pad	A	B	C	D	E
SDR0603, SDR0604	1	1.7	6.0	5.8	2.15	—
SDR0805	1	2.4	7.8	8.0	2.7	—
SDR1006	1	2.8	10.0	10.0	3.6	—
SDR0906	2	14.7	10.3	2.2	1.0	2.5

These pad dimensions are only for standard pattern and the characteristics are not guaranteed, which you are suggested to confirm before use.

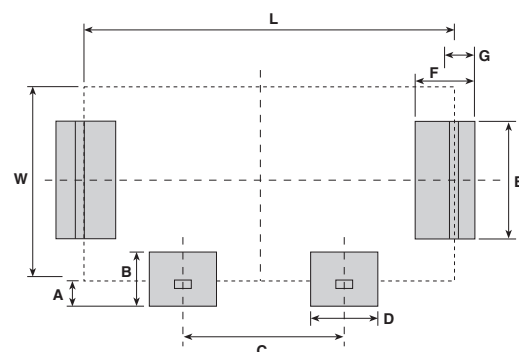
### current sense resistor—CSR

Dimensions inches (mm)									
Type	L	W	A	B	C	D	E	F	G
CSR1	.393 (10.0)	.236 (6.0)	.039 (1.0)	.078 (2.0)	.196 (5.0)	.062 (1.6)	.118 (3.0)	.078 (2.0)	.039 (1.0)
CSR2	.472 (12.0)	.314 (8.0)	.062 (1.6)	.125 (3.2)	.236 (6.0)	.086 (2.2)	.208 (5.3)	.090 (2.3)	.045 (1.15)

### SDR



### CSR



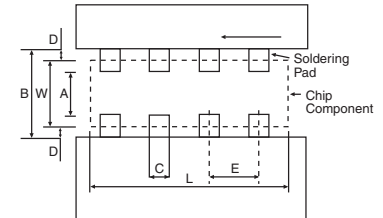
Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use.

1/06/13

### resistor arrays—CN

Type	Style	Dimensions						
		Component Size		A	B	C	D	E
		L	W					
CN	1H2N	0.8	0.6	0.3	0.9	0.9	0.3	0.5
	1H4N	1.4					0.2	0.4
	1E2K	0.5 X n	1.0	0.5	1.5	0.4	0.25	0.67
	1E4K					0.3	0.25	0.5
	1F8K	3.8	1.6	1.0	2.6	0.3	0.5	0.5
	1JA/K	0.8 X n	1.6	1.0	2.6	0.6	0.5	0.8
	1E2	0.5 X n	1.0	0.5	1.5	0.3	0.25	0.5
	1E4							
	2B4A	5.1	3.1	2.1	4.1	0.9	0.5	1.27
	1J	0.8 X n	1.6	0.8	2.6	0.4	0.5	0.8
	2A	1.27 X n	2.0	1.0	3.0	0.65	0.5	1.27
	2B		3.2	2.2	4.2	0.65	0.5	1.27

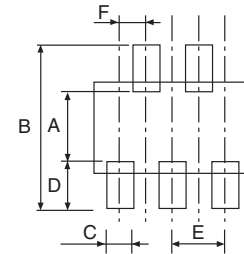
### Chip Networks



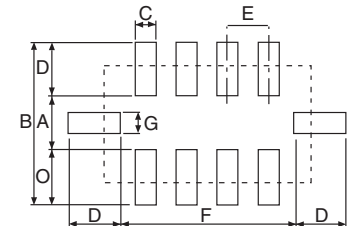
### resistor arrays—CN

Type	Style	Dimensions						
		Component Size		A	B	C	D	E
		L	W					
CND	1J10K	3.2	1.6	0.9	2.6	0.4	0.5	0.64
	2B10	6.4	3.1	2.1	4.1	0.6	0.5	1.27
CNN	2A	2.54	2.0	1.2	2.8	0.6	0.4	1.27

### CNB2E5Z, CNB2B9Z



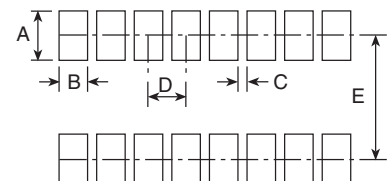
### CND1J10Y, CND2A10Y



### thick film resistor—MRGF

Type	Dimensions					
	Component Size	A	B	C	D	E
MRGF16	11.0 X 7.7	1.27	0.76	0.51	1.27	7.62

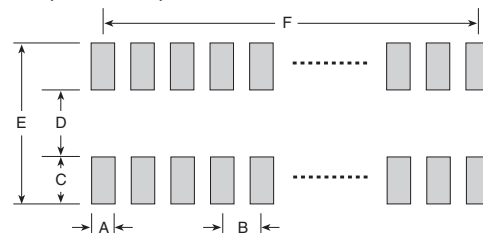
### MRGF



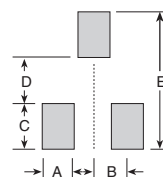
### integrated passive devices—SOIC, TSSOP, QSOP & SOT23

Chip Size	Dimensions inches (mm)					
	A	B	C	D	E	F
N08	.028 (0.7)	.050 (1.27)	.094 (2.4)	.098 (2.5)	.287 (7.3)	.150 (3.81)
N14	.028 (0.7)	.050 (1.27)	.094 (2.4)	.098 (2.5)	.287 (7.3)	.300 (7.62)
N16	.028 (0.7)	.050 (1.27)	.094 (2.4)	.098 (2.5)	.287 (7.3)	.350 (8.89)
Q16	.012 (0.3)	.025 (0.63)	.050 (1.27)	.180 (4.56)	.280 (7.1)	.175 (4.45)
Q20	.012 (0.3)	.025 (0.63)	.050 (1.27)	.180 (4.56)	.280 (7.1)	.225 (5.72)
Q24	.012 (0.3)	.025 (0.63)	.050 (1.27)	.180 (4.56)	.280 (7.1)	.275 (6.99)
SOT23	.035 (0.9)	.037 (0.95)	.055 (1.4)	.031 (0.8)	.141 (3.6)	—

#### SOIC, TSSOP, QSOP

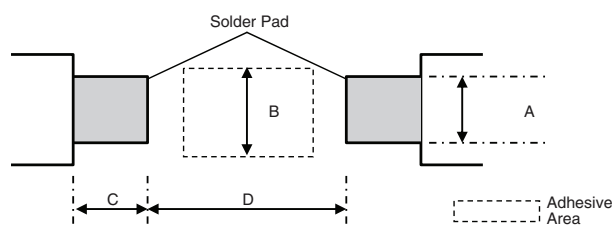


#### SOT23



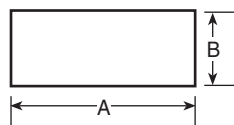
### melf type components—RD41, RN41, RM41, MLT, CC

Type	Style	Dimensions millimeters				
		Component Size	A	B	C	D
RD41 RN41 RM41 MLT CC	2A 10	2.0 X 1.25	1.3	1.3	2.0	1.3
	2ES 12M	3.5 X 1.40	1.5	2.2	1.5	2.0
	2D 20	3.2 X 1.55	1.5	2.2	1.5	2.0
	2E 25	5.9 X 2.2	2.0	3.0	3.0	4.0
	2H	5.9 X 2.2	2.0	3.0	3.0	4.0



### other chips—RCS, RCT, RCU, RCW

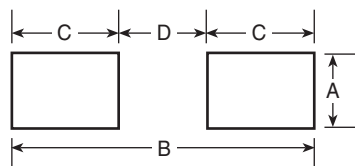
Type	Dimensions millimeters	
	A	B
RCS	4.1-4.3	1.4-1.6
RCT	2.9-3.1	1.05-1.25
RCU	2.5-2.7	0.6-0.8
RCW	4.1-4.3	1.4-1.6



### ceramic chip capacitors

Component pads should be designed to achieve good solder filets and minimize component movement during reflow soldering. Pad dimensions are given below for multilayer ceramic capacitors for both reflow and wave soldering. The basis for these designs is:

- Pad width equal to component width. It is permissible to decrease this to as low as 85% of component width but it is not advisable to go below this.
- Pad overlap 0.5mm beneath component
- Pad extension 0.5mm beyond components for reflow and 1.0mm for wave soldering

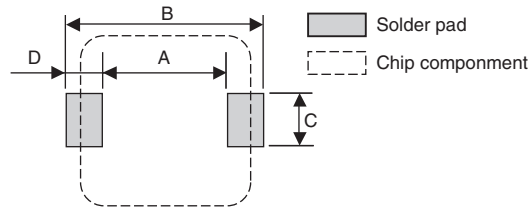


Case Size	Dimensions inches (mm)			
	A	B	C	D
0402	0.02 (0.50)	0.07 (1.70)	0.02 (0.60)	0.02 (0.50)
0603	0.03 (0.75)	0.09 (2.30)	0.03 (0.80)	0.03 (0.70)
0805	0.05 (1.25)	0.12 (3.00)	0.04 (1.00)	0.04 (1.00)
1206	0.06 (1.60)	0.16 (4.00)	0.04 (1.00)	0.09 (2.00)
1210	0.10 (2.50)	0.16 (4.00)	0.04 (1.00)	0.09 (2.00)

Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use.

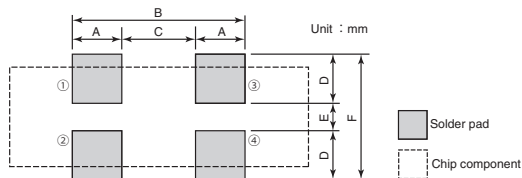
1/06/13

### surface mount inductors—LKS



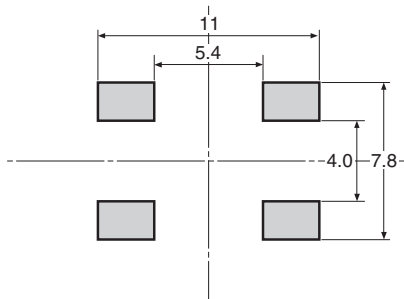
Case Size	Dimensions inches (mm)			
	A	B	C	D
0745	0.22 (5.5)	0.34 (8.70)	0.09 (2.30)	0.06 (1.60)
1045	0.22 (5.5)	0.42 (10.7)	0.14 (3.60)	0.10 (2.60)
1260	0.37 (9.5)	0.55 (13.9)	0.21 (5.30)	0.09 (2.20)

### surface mount inductors—KT11835



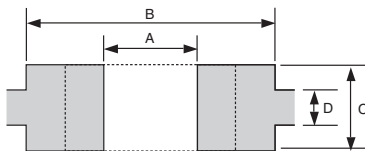
Case Size	Dimensions inches (mm)					
	A	B	C	D	E	F
11835	0.07 (1.90)	0.27 (6.80)	0.12 (3.00)	0.07 (1.90)	0.03 (0.80)	0.18 (4.60)

### surface mount inductors—KTZ1030



Type	Dimensions millimeters			
	A	B	C	D
KTZ1030	11	5.4	4.0	7.8

### fuses—SF45



Case Size	Dimensions inches (mm)			
	A	B	C	D
SF45	0.14 (3.50)	0.22 (5.50)	0.13 (3.20)	0.04 (1.00)

These pad dimensions are only for standard pattern and the characteristics are not guaranteed, which you are suggested to confirm before use.